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(PTO Form 1449 modified)

Sheet 1 of 2 sheet(s)

**SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT BY
APPLICANT**

(Use several sheets if necessary)



Examiner Dung Anh Le

Docket No. AMAT/6392/DSM/LO W K/JW	Serial No. 10/010,950
Applicant Xia, et al.	Confirmation No.: 5694
Filing Date November 13, 2001	Group 2818

U.S. Patent Documents

*Examiner Initial	Document Number	Issue Date	Applicant(s) Name	Class	Subclass	Filing Date If Appropriate
DAL	A1 6,465,366	10/15/2002	Nemani, et al.	438	778	09/12/2000
	A2 5,926,740	07/20/1999	Forbes, et al.	438	763	10/27/1997
	A3 5,876,891	03/02/1999	Takimoto, et al.	430	71	05/26/1995
	A4 5,710,067	01/20/1998	Foote, et al.	437	238	06/07/1995
	A5 5,638,251	06/10/1997	Goel, et al.	361	313	10/03/1995
	A6 5,607,773	03/04/1997	Ahlburn, et al.	428	427	12/20/1994
	A7 5,494,712	02/27/1996	Hu, et al.	427	589	11/17/1997
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	A9 5,242,530	09/07/1993	Batey, et al.	156	613	08/05/1991
	A10 5,224,441	07/06/1993	Felts, et al.	118	718	09/27/1991
	A11 5,011,706	04/30/1991	Tarhay, et al.	427	39	04/12/1989
	A12 4,759,947	07/26/1988	Ishihara, et al.	427	38	10/04/1985
Xia	A13 4,532,150	07/30/1985	Endo, et al.	427	39	12/22/1983

Foreign Patent Documents

*Examiner Initial	Document Number	Date	Country	Class	Subclass	Translation
DAL	B1 09-008031	01/10/1997	JP	H01L	21/316	<input type="checkbox"/> YES <input checked="" type="checkbox"/> NO
	B2 00/19498	04/06/2000	WO	H01L	21/027	<input type="checkbox"/> YES <input checked="" type="checkbox"/> NO
	B3 1 176 226	01/30/2002	EP	C23C	16/32	<input type="checkbox"/> YES <input checked="" type="checkbox"/> NO

OTHER ART

*Examiner Initial Including Author, Title, Date, Pertinent Pages, Etc.

C1 U.S. Patent Application No. 09/270,039, filed on March 16, 1999.

C2 Written Opinion from PCT/US99/22424, dated April 5, 2001.

C3 PCT Partial International Search Report for US99/22317 dated March 21, 2000.

Examiner

Date Considered

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*Examiner Initial		Document Number	Issue Date	Applicant(s) Name	Class	Subclass	Filing Date If Appropriate
DL	A1	2003/0139035	07/24/2003	Yim, et al.	438	643	09/19/2002
DL	A2	2003/0129827	07/10/2003	Lee, et al.	438	629	07/15/2002
DL	A3	2003/0111730	06/19/2003	Takeda, et al.	257	758	05/28/2001
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DL	A10						
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OTHER ART

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DL	C4	PCT International Search Report for US99/22425 dated February 11, 2000.
DL	C5	Dijkstra, et al. "Optimization of Anti-Reflection Layers for Deep UV Lithography", Proceeding of SPIE Optica/Laser Microlithography, Bellingham, SPIE, Volume 1674, (1992) Pages 362-375.
DL	C6	Omar, M.A. "Elementary Solid State Physics: Principles and Applications," Lowell Technological Institute, Addison-Wesley Publishing Company, 1975, Pages 124 & 125.
DL	C7	Fukuda, et al. "Highly Reliable SiOF Film Formation by ECR-CVD using SiF ₂ H ₂ ", (1996) Symposium on VLSI Technology Digest of Technical Papers, IEEE, Pages 114-115.
DL	C8	PCT International Search Report for US/02/40034, dated May 19, 2003.
DL	C9	Wu, et al, "Advanced Metal Barrier Fee Cu Damascene Interconnects with PECVD Silicon Carbide Barriers for 90/65-nm BEOL Technology", 2002 IEEE Pages 595-598.
Examiner	DL	Date Considered Feb -04

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